

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4403357

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MANU J. PRAKUZHY	03/29/2017
SIVA P. GURRUM	03/29/2017
DARYL R. HEUSSNER	04/04/2017
STEFAN W. WIKTOR	04/13/2017
KEN PHAM	03/24/2017
RECEIVING PARTY DATA	
Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD, MS 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15487186
CORRESPONDENCE DATA	
Fax Number:	(214)567-2228
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214 479 1238
Email:	uspto@ti.com
Correspondent Name:	TEXAS INSTRUMENTS INCORPORATED
Address Line 1:	P O BOX 655474, MS 3999
Address Line 4:	DALLAS, TEXAS 75265
ATTORNEY DOCKET NUMBER:	TI-76969
NAME OF SUBMITTER:	ROSE ALYSSA KEAGY
SIGNATURE:	/ROSE ALYSSA KEAGY/
DATE SIGNED:	05/08/2017
Total Attachments: 12	
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source=TI-76969-Assignment-Pham#page3.tif

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at Texas Instruments Incorporated, 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to Provisional Application Number 62/385,499, filed September 9, 2016, European Application Number _____, filed _____,

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

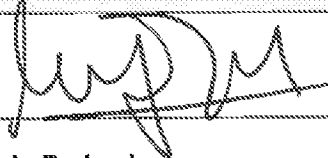
I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.


I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE	Spot-Solderable Leads for Semiconductor Device Packages		
NONPROVISIONAL APPLICATION NO.		FILING DATE	

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Manu J. Prakuzhy
DATE	March, 29, 2017
RESIDENCE (CITY AND STATE)	Allen, TX

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Siva P. Gurrum
DATE	March, 29, 2017
RESIDENCE (CITY AND STATE)	Allen, TX

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daryl R. Heussner
DATE	
RESIDENCE (CITY AND STATE)	Allen, TX

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Stefan W. Wiktor
DATE	
RESIDENCE (CITY AND STATE)	Raleigh, NC

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Ken Pham
DATE	
RESIDENCE (CITY AND STATE)	San Jose, CA

After recording, return Assignment to:

Texas Instruments Incorporated
12500 TI Boulevard, M/S 3999
Dallas, TX 75243
U.S.A.

Application No.: _____

Attorney Docket No. TI-76969

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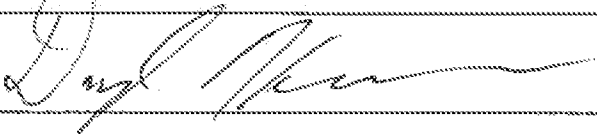
TITLE	Spot-Solderable Leads for Semiconductor Device Packages		
NONPROVISIONAL APPLICATION NO.		FILING DATE	

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PRINTED NAME OF INVENTOR	Manu J. Prakuzhy
DATE	
RESIDENCE (CITY AND STATE)	Allen, TX

Application No.: _____

Attorney Docket No. **TI-76969**

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Siva P. Gurrum
DATE	
RESIDENCE (CITY AND STATE)	Allen, TX

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daryl R. Heussner
DATE	4/4/17
RESIDENCE (CITY AND STATE)	Allen, TX

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Stefan W. Wiktor
DATE	
RESIDENCE (CITY AND STATE)	Raleigh, NC

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Ken Pham
DATE	
RESIDENCE (CITY AND STATE)	San Jose, CA

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SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Ken Pham
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